

DAM009N150P1

N-Channel Enhancement Mode MOSFET

Preliminary

Features

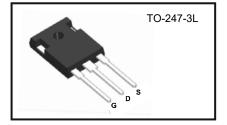
- Advanced Process Technology
- Ultra Low On-Resistance
- Dynamic dv/dt Rating
- · Fast Switching
- · Fully Avalanche Rated

Applications

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible Power Supply

G





Package Dimensions

	UNIT	:mm				
Symbol	MIn.	Nom	Max.			
Α	4.80	5.00	5.20			
A1	2.21	2.41	2.61			
A2	1.85	2.00	2.15			
b	1.11	1.21	1.36			
b2	1.91	2.01	2.21			
b4	2.91	3.01	3.21			
С	0.51	0.61	0.75			
D	20.70	21.00	21.30			
D1	16.25	16.55	16.85			
E	15.50	15.80	16.10			
E1	13.00	13.30	13.60			
E2	4.80	5.00	5.20			
E3	2.30	2.50	2.70			
е		5.44BSC				
L	19.62	19.92	20.22			
L1	-	-	4.30			
ØΡ	3.40	3.60	3.80			
ØP1	-	-	7.30			
S		6 15BSC				

Absolute Maximum Ratings

(Tc = 25°C unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Drain Source Voltage	V DS	1500	v
Gate Source Voltage	Vgs	± 30	v
Drain Current Continuous @ Tc = 25°C	lo	9	A
Drain Current Pulsed	Ірм	36	A
Single Pulse Avalanche Energy	Eas	450	mJ
Power Dissipation @ Tc= 25°C	P□	320	w
Storage Temperature Range	Тѕтс	-55 to +150	°C
Operating Junction Temperature Range	TJ	-55to +150	°C
Thermal Resistance Junction to Case	R∂Jc	0.39	°C/W



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Electrical Characteristics @ Tc =25°C (unless otherwise specified)

		<u>-</u>		1		
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
OFF Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V · I _D =0.25mA	1500	-	-	٧
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} =0V · V _{DS} =1500V	-	-	1	μΑ
Gate To Source Forward Leakage	I _{GSS}	V _{GS} =±30V, V _{DS} =0V	-	-	±100	nA
ON Characteristics						
Gate Threshold Voltage	$V_{GS(th)}$	V _{DS} =V _{GS} , I _D =0.25mA	2.5	-	4.5	٧
Drain-Source On-State Resistance**	R _{DS(on)}	V _{GS} =10V , I _D =5.4A	-	2.8	4	Ω
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} =25V	-	3380	-	
Output Capacitance	C _{oss}	V _{GS} =0V	-	178	-	pF
Reverse Transfer Capacitance	C _{rss}	Freq.=1MHz	-	54	-	
Switching Characteristics						
Turn-On Delay Time	t _{d(on)}	V _{DD} =750V	-	67	-	
Rise Time	t _r	V _{GS} =10V	-	189	-	
Turn-Off Delay Time	t _{d(off)}	I _D =9A	-	84	-	ns
Fall Time	t _f	$R_G = 25\Omega$	-	116	-	
Total Gate Charge	Qg	V _{DS} =750V	-	70	-	
Gate to Source Charge	Q _{gs}	V _{GS} =10V	-	21	-	nC
Gate to Drain Charge	\mathbf{Q}_{gd}	I _D =9A	-	23	-	
Drain-Source Diode Characteristics and	d Maximum Ra	atings				
Diode Forward Voltage**	V _{SD}	V _{GS} =0V • I _S =3A	-	-	1.3	٧
Reverse Recovery Time	T _{rr}	V _{GS} =0V	-	461	-	ns
Reverse Recovery Charge	Q _{rr}	- I⊧=3A di/dt=100A/µs	-	3.36	-	μC

^{*}Repetitive Rating: Pulse width limited by maximum junction temperature

^{**}Pulse Width < 300 μ s, Duty Cycle < 2%.



Typical Performance Characteristics

Figure 1. Output Characteristics

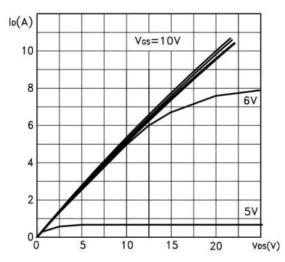


Figure 3. Normalized Breakdown Voltage vs Junction Temperature

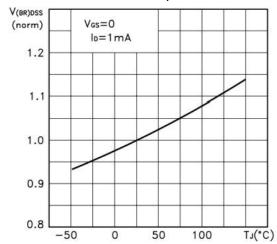


Figure 5. Gate Charge Characteristics

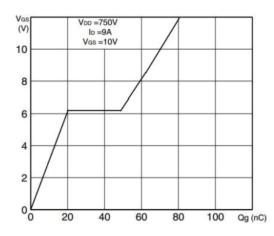


Figure 2. Drain-to-Source On Resistance vs Drain Current

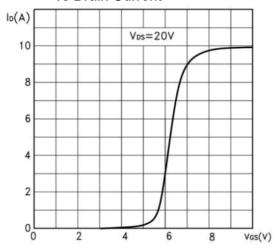


Figure 4. Drain-to-Source On Resistance vs Drain Current

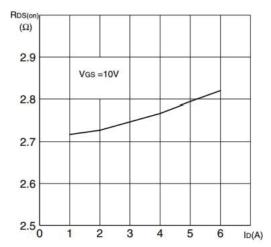
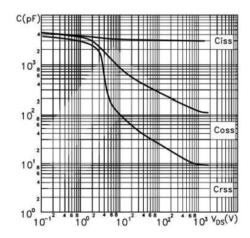


Figure 6. Capacitance Characteristics



Rev1.0 - 3 - May 2024



Typical Performance Characteristics

Figure 7. Normalized Threshold Voltage vs Junction Temperature

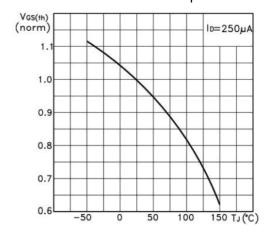


Figure 9. Body Diode Forward Voltage vs Source Current and Temperature

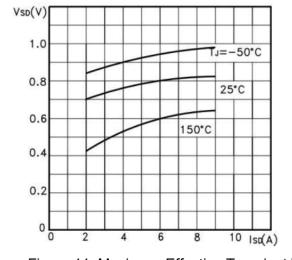


Figure 8. Normalized On Resistance vs Junction Temperature

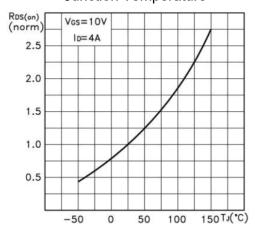


Figure 10. Maximum Safe Operating Area

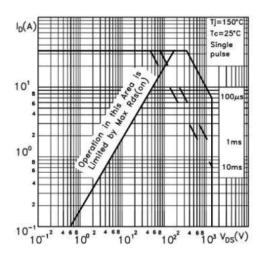
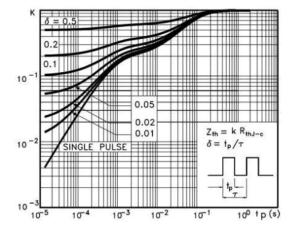


Figure 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case







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